

2027 第二届杭州国际
The 2nd Hangzhou International

半导体与集成电路产业创新展览会

Semiconductor and Integrated Circuit Industry Innovation Exhibition

2027.05.27-29

杭州大会展中心-浙江

Hangzhou Grand Convention and Exhibition Center-Zhejiang

批准单位 / Approved by

中华人民共和国商务部
Ministry of Commerce of the
People's Republic of China

指导单位 / Directed by

中国半导体行业协会
China Semiconductor Industry Association

主办单位 / Hosted by

浙江省半导体行业协会
Zhejiang Semiconductor
Industry Association

上海高登会展集团有限公司
Golden Conference & Exhibition Group

协办单位 / Co-organized by

杭州国家“芯火”双创基地（平台）
Hangzhou National Xinhua Platform for Innovation and Entrepreneurship

承办单位 / Organized by

杭州长芯国际会展管理有限公司
Hangzhou SICE International Exhibition Management Co., Ltd.

**芯聚钱塘
智联全球**

www.sicexpo.cn

展会概况

Exhibition Background

随着全球数字经济、人工智能、新能源汽车、高端先进制造浪潮全速迭代，集成电路作为支撑国家科技自立自强的核心根基，正式迈入国产化替代提速、全产业链协同共进的黄金发展时代。长三角集聚国内配套最完善、资源最富集的集成电路产业集群，而杭州坐拥“中国数字经济第一城”得天独厚的产业禀赋，集聚海量终端应用需求、顶尖高校科研平台与多元产业资本，是串联芯片设计、晶圆制造、封装测试、半导体设备材料与下游千行应用的核心战略枢纽，为产业协同创新、供需精准对接提供无可替代的发展沃土。2026首届杭州长芯展盛大收官，交出一份震撼行业的亮眼答卷：展会坐拥近30000m²专业展示空间，汇聚173家海内外行业龙头与顶尖科研机构集中亮相，联动600余家上下游优质企业同台交流；累计吸引3万人次精准专业观众莅临观展洽谈，现场达成合作意向总额高达139亿元，商贸落地成效斐然。同期重磅举办16场高规格产业高峰论坛，创新构建“展览+论坛+供需对接+产业招商+人才引智”五位一体综合产业服务平台，凭借专业化、高实效的办展实力，收获全国半导体行业高度赞誉与一致认可。承首届丰硕产业成果，再启全新产业华章！为持续打造链接全球、辐射全国的集成电路顶级交流合作载体，2027第二届杭州国际半导体与集成电路产业创新展览会（杭州长芯展）正式开启全球展商招商通道。展会定于2027年5月27日-29日落地杭州大会展中心，以“芯聚钱塘，智联全球”为核心宗旨，依托杭州数字经济产业优势与长三角集成电路集群强大势能，诚邀全球半导体全产业链企业赴钱塘之约，聚芯聚力，共启国产半导体产业高质量发展新征程！

Driven by the rapid evolution of the global digital economy, artificial intelligence (AI), new energy vehicles (NEVs), and advanced manufacturing, the integrated circuit (IC) industry, as the cornerstone of China's technological self-reliance and innovation, has entered a golden era characterized by accelerated import substitution and coordinated development across the entire industrial value chain. The Yangtze River Delta is home to China's most comprehensive and resource-rich integrated circuit industrial cluster. Hangzhou, renowned as China's leading digital economy hub, possesses unparalleled industrial advantages, bringing together massive end-user demand, world-class universities and research institutions, and diversified industrial capital. Serving as a strategic hub connecting IC design, wafer fabrication, semiconductor packaging and testing, equipment and materials, and a wide range of downstream applications, Hangzhou provides an unparalleled platform for collaborative innovation, precise business matchmaking, and high-quality industrial development. The Hangzhou International Semiconductor and Integrated Circuit Industry Innovation Exhibition 2026 concluded with remarkable success, delivering outstanding results that impressed the entire industry. With a total exhibition area of 30,000 square meters, the event bringing together 173 leading domestic and international enterprises and prestigious research institutions, while connecting more than 600 high-quality upstream and downstream companies across the semiconductor value chain. It attracted over 30,000 professional visitors to attend, with intended cooperation agreements reaching RMB 13.9 billion, demonstrating exceptional commercial achievements. A total of 16 high-level industry forums were held concurrently, creating a comprehensive industrial service platform that integrated exhibitions, conferences, business matchmaking, industrial investment promotion, and talent recruitment. With its highly professional organization and outstanding business outcomes, the exhibition earned widespread recognition and high acclaim from across China's semiconductor industry. Based on the remarkable achievements of the inaugural edition, the exhibition embarks on a new chapter of industrial innovation. To further establish a world-class platform for global collaboration and industry exchange, the 2nd Hangzhou International Semiconductor and Integrated Circuit Industry Innovation Exhibition 2027 has officially opened the global exhibitor registration and recruitment. The exhibition will take place from May 27 to 29, 2027, at the Hangzhou Grand Convention and Exhibition Center. Taking "Gathering Chips in Qiantang, Connecting Intelligence Worldwide" as its theme, relying on Hangzhou's strengths in the digital economy and the robust momentum of the Yangtze River Delta's integrated circuit industry cluster, the event will bring together leading enterprises, innovators, and industry experts from across the global semiconductor value chain to strengthen collaboration, accelerate innovation, and jointly shape the future of China's high-quality semiconductor industry development.

2026首届展会成果 2026 INAUGURAL RESULTS



30,000m²
展览面积
Exhibition Area



173家
参展企业
Exhibitors



600+家
产业链上下游企业
Enterprises Upstream and Downstream
of the Industrial Chain



30,000人次
专业观众到场
Professional Visitors



139亿元
达成合作意向
Cooperation Intention



16场
高峰论坛活动
Forums and Conferences

展会核心使命 与举办初衷

Core Mission and
Purpose of the Exhibition



立足长三角集成电路产业核心区位，响应国家集成电路自主可控、科技自立自强重大战略部署，搭建集成果展示、商贸交易、技术研讨、资本对接、人才引进于一体的国际化产业平台

Positioned at the core of the Yangtze River Delta, China's premier integrated circuit manufacturing and innovation cluster, and in response to the national strategies for semiconductor self-reliance, technological self-sufficiency, and resilient supply chain development, the show aims to establish a world-class international platform that integrates technology exhibition, business matchmaking, trade collaboration, investment promotion, innovation exchange, and talent development, fostering deeper cooperation across the global semiconductor ecosystem.



贯通芯片设计、晶圆制造、封测、设备材料、EDA、先进封装、AI芯片全产业链，集中展示国产半导体前沿技术突破与创新成果

Showcase the entire semiconductor value chain covering IC design, wafer fabrication, packaging & testing, semiconductor equipment and materials, EDA software, advanced packaging, compound semiconductors, and AI chips, highlighting China's latest technological breakthroughs, innovative products, and industrial achievements.



推动上下游企业精准供需匹配，打通信息壁垒，促成项目签约与长期战略合作，加速高端芯片、核心元器件在新能源汽车、人形机器人、高端医疗等场景商业化落地

Facilitate efficient business matching between upstream and downstream enterprises, foster project partnerships and long-term strategic collaborations, and accelerate the commercialization and large-scale deployment of advanced chips and critical semiconductor components in high-growth sectors such as NEVs, humanoid robotics, and advanced medical technologies.



联动上海、无锡、苏州等长三角产业集群，深化区域产业协同，补齐产业链短板，构建安全稳定、自主可控的本土半导体供应链体系

Promote deeper collaboration among the leading semiconductor clusters across the Yangtze River Delta, including Shanghai, Wuxi, Suzhou, Hangzhou, to enhance regional industrial integration, strengthen supply chain coordination, address critical gaps across the value chain, and build a secure, resilient, and self-reliant domestic semiconductor supply chain ecosystem.



汇聚院士、行业专家、龙头企业、创投机构开展高端论坛，研判产业趋势、共解技术瓶颈，推动产业链、创新链、资本链、人才链、政策链五链融合

Bring together academicians, industry experts, leading enterprises, research institutions, venture capital firms, and government representatives to exchange insights on emerging industry trends, tackle key technological challenges, and accelerate the convergence of industry, innovation, capital, talent, and policy, building a collaborative and innovation-driven semiconductor ecosystem.



依托杭州数字经济海量下游应用市场与顶尖高校科研资源，助力企业拓客接单、品牌升级、招才引智、融资落地，引导产业向高端化、智能化、国产化纵深发展

Relying on Hangzhou's robust digital economy, extensive downstream application markets, and world-class research universities, the exhibition empowers enterprises to expand market opportunities, strengthen brand influence, attract top-tier talent, secure investment, and accelerate business growth. It further supports the industry's transition toward higher-value manufacturing, intelligent innovation, and greater technological self-reliance.



强化长三角世界级集成电路产业集群竞争力，畅通国内国际产业循环，推动国内半导体产业深度融入全球价值链，助力行业高质量高速发展

Strengthen the global competitiveness of the Yangtze River Delta as a world-class integrated circuit cluster, foster greater connectivity between domestic and international semiconductor ecosystems, deepen China's integration into the global semiconductor value chain, and drive the industry's high-quality development.

往届硬核实力 本届全新升级

Building on the Success of the Inaugural Edition,
with a Comprehensive Upgrade for 2027

首届展会已交出亮眼产业答卷，2027第二届全面升级资源、流量、对接服务：

Building on the remarkable achievements of the inaugural edition, the 2nd exhibition returns with a comprehensive upgrade in industry resources, traffic generation, and business matchmaking services.

I 全产业链完整展品矩阵 | Comprehensive Semiconductor Industry Chain Showcase

覆盖 EDA 工具、芯片设计、晶圆制造、先进封装测试、半导体高端设备、关键电子化学品、第三代半导体、Chiplet、AI 算力芯片、存算一体、光子集成、RISC-V 生态及全场景终端应用，完整覆盖产业上中下游。

The exhibits cover the entire semiconductor value chain, including EDA tools, IC design, wafer fabrication, advanced packaging and testing, high-end semiconductor manufacturing equipment, key electronic chemicals, third-generation semiconductors, Chiplet technologies, AI computing chips, computing-in-memory, photonic integration, the RISC-V ecosystem, and a full spectrum of end-use applications across diverse industries.

II 高含金量精准专业观众邀约 | Targeted Professional Buyer Invitation Plan

定向全球邀约半导体制造、封测、设备材料厂商、整车企业、AI 算力服务商、医疗电子、航空航天、科研院所、产业投资机构采购负责人与技术决策人；严控观众质量，杜绝无效流量，保障高效商务洽谈。

Procurement executives and technical decision-makers from semiconductor manufacturers, OSAT providers, equipment and material suppliers, automotive OEMs, AI computing service providers, medical electronics companies, aerospace enterprises, research institutes, universities, and industrial investment organizations will invited to attend the show with the purpose of visiting and purchasing. Based on rigorous attendee qualification and quality control, the exhibition ensures a high-caliber professional audience, eliminates ineffective traffic, and creates an efficient platform for business networking and commercial collaboration.

III 全域媒体矩阵曝光 | Extensive Global Media Exposure

联动超过300海内外垂直行业媒体、短视频平台、行业直播、产业专栏全周期宣传，企业新品、技术方案、品牌故事全网立体化传播，快速提升行业知名度。

Powered by a network of more than 300 domestic and international industry media outlets, short-video platforms, livestream channels, and professional publications, the exhibition delivers a comprehensive, full-cycle media campaign that amplifies product launches, technology innovations, and brand stories across multiple channels, helping exhibitors enhance brand visibility, strengthen industry influence, and expand market presence.

IV 重磅同期论坛，把握行业前沿风向 | High-Level Concurrent Conferences

同期举办九大顶级产业峰会：全国集成电路人才生态大会、杭州新纪元半导体发展高峰论坛、EDA创新生态论坛、半导体材料装备论坛、光电集成论坛、先进封装技术峰会、智能制造论坛、RISC-V生态共建峰会、产业投资对接会。院士、行业专家、头部企业高管、创投大咖齐聚，解读政策、研判技术趋势、分享国产化落地路径。

During the exhibition, nine premier industry conferences will be held, covering IC talent development, semiconductor innovation, EDA, semiconductor materials and equipment, photonic integration, advanced packaging, intelligent manufacturing, the RISC-V ecosystem, and investment matchmaking. Renowned academicians, industry experts, executives from leading enterprises, and investment leaders will share policy insights, discuss emerging technology trends, and explore pathways for semiconductor localization and industrial innovation.

展品大类

Major Exhibits



IC设计 IC Design

IC设计（模拟和功率芯片、AI算力芯片、存储芯片、汽车电子芯片、智能家电芯片、人工智能芯片、ASIC芯片、传感器芯片、光电芯片、生物芯片、类脑芯片、量子芯片）；

IC design (analog and power chips, ai computing chips, memory chips, automotive electronics chips, smart home appliance chips, AI chips, asic chips, sensor chips, photonic chips, biochips, neuromorphic chips, quantum chips)



IC制造 IC Manufacturing

晶圆制造、分立器件、光电器件、传感器产品；

Wafer fabrication, discrete devices, optoelectronic devices, sensor products



IC封装及测试 IC Packaging and Testing

DIP、SOP、QFP、SIP、BGA等传统封装；倒装、晶圆级封装、2.5D/3D先进封装(TSV及TGV)、Chiplet等先进封装；IC前后端测试服务；

Traditional packaging (DIP, SOP, QFP, SIP, BGA); advanced packaging (flip-chip, wafer-level packaging, 2.5d/3d packaging with tsv and tgv, chiplet technology); ic testing services (front-end and back-end)



EDA&IP EDA&IP



半导体设备及零部件 Semiconductor Equipment and Components

晶圆加工过程中所需的各种精密设备、半导体封装设备、测试设备；密封圈、精密轴承、金属零部件、Valve阀、硅/SiC件、Robots、石英件、过滤器、射频电源、陶瓷件、ESC静电吸盘、压力Gauge、泵、MFC流量计、步进马达、运动控制、伺服电机、直线模组、无尘拖链、封装模具、制冷设备、感应加热器等半导体零部件；

Precision equipment for wafer fabrication, semiconductor packaging systems, and test equipment; essential components including sealing rings, precision bearings, metal components, valves, silicon/SiC parts, robots, quartz components, filters, RF power supplies, ceramic components, electrostatic chucks (ESCs), pressure gauges, pumps, mass flow controllers (MFCs), stepper motors, motion control systems, servo motors, linear modules, cleanroom cable carriers, packaging molds, refrigeration equipment, induction heaters, and other critical semiconductor parts.

展品大类

Major Exhibits



半导体材料

Semiconductor Materials

单晶硅、硅片等硅基材料；抛光垫、掩膜版、溅射靶材、光刻胶、薄膜沉积材料、前驱体材料、特种气体、抛光液、湿电子化学品等工艺辅助材料；陶瓷封装材料、键合丝、引线框架、封装基板、塑封材料、高性能塑料等封装材料等；

Silicon-based materials including monocrystalline silicon, silicon wafers; process auxiliary materials including polishing pads, photomasks, sputtering targets, photoresists, thin-film deposition materials, precursor materials, specialty gases, polishing slurries, wet electronic chemicals; packaging materials including ceramic packaging materials, bonding wires, lead frames, packaging substrates, molding compounds, high-performance plastics.



化合物半导体材料及产品

Compound Semiconductor Materials and Products

化合物半导体（如磷化铟、碳化硅、氮化镓、氧化镓等）衬底及外延片材料生产企业及其器件、模组产品；

Enterprises specializing in compound semiconductor substrates and epitaxial wafers (e.g., indium phosphide, silicon carbide, gallium nitride, and gallium oxide), along with related devices and module products.



下游芯片应用

Downstream Chip Applications

物联网、人工智能、智能网联汽车、健康医疗、具身智能、消费电子、网络通信、仪器仪表等产品；

The Internet of Things (IoT), AI, intelligent connected vehicles (ICV), healthcare, embodied ai, consumer electronics, network communications, and instrumentation.



配套设施与服务

Supporting Facilities and Services

各地芯火平台、半导体协会、产业联盟、半导体研究院、中试产线及高校、投融资机构、环保企业、电子类建筑施工企业、一般商业服务/咨询机构、销售、标准化制定及物流冷链等支撑服务企业。

Xinhuo platform, semiconductor associations, industry alliances, semiconductor research institutes, pilot production lines and universities, investment and financing institutions, environmental protection companies, electronic construction enterprises, general business services/consulting firms, sales organizations, standards development bodies, and logistics and cold chain enterprises.

展区设置

Exhibition Areas

- | | | |
|---|-------------|---|
| 1 | IC设计 | IC Design Pavilion |
| 2 | IC制造 | IC Manufacturing Pavilion |
| 3 | IC封装及测试 | IC Packaging and Testing Pavilio |
| 4 | EDA&IP | EDA&IP Pavilion |
| 5 | 半导体设备及零部件 | Semiconductor Equipment and Components Pavilion |
| 6 | 半导体材料 | Semiconductor Materials Pavilion |
| 7 | 化合物半导体材料及产品 | Compound Semiconductors Materials and Products Pavilion |
| 8 | 下游芯片应用 | Chip Applications Pavilion |
| 9 | 配套设施与服务 | Supporting Facilities and Services Pavilion |

聚焦“高端芯”与“国产替代”的最新突破，打造行业最前沿的技术展示平台。

Focusing on the latest breakthroughs in “high-end chips” and “domestic substitution,” the event strives to provide a cutting-edge platform to showcase industry-leading technologies.

展会费用

Participation Fees

Company Type 企业性质	Booth Type 展位类别	Ecology Pavilion 生态展区	Industry Pavilion 产业展区
For domestic enterprises 国内企业	Indoor Raw Space 室内光地	3000(RMB)/m ² /展期/Expo	1600(RMB)/m ² /展期/Expo
	Standard Booths 标准展位	29800(RMB)/3mx3m/展期/Expo	16800(RMB)/3mx3m/展期/Expo
For overseas enterprises 国外企业	Indoor Raw Space 室内光地	680(USD)/m ² /展期/Expo	480(USD)/m ² /展期/Expo
	Standard Booths 标准展位	6800(USD)/3mx3m/展期/Expo	4800(USD)/3mx3m/展期/Expo

Note: The raw space (minimum 36 sq.m.) only supplies a show space excluding stand frames, show equipment, carpet and power supply, etc.(Double opening booths will be charged an additional 20% service fee)

注：(最少36平方米起租)“光地”只提供参展面积，不包括展架、展具、地毯、电源等。(双开口展位需加20%服务费)

赞助方案

Sponsorship Proposal

01 赞助条例 Sponsorship Packages

赞助项目	金额(万元)	规格/权益说明	限量
展会协办冠名	60	展会协办单位	独家
展会支持单位	40	展会支持单位	限3家
钻石·独家总冠名赞助	168	享有XX品牌之夜	独家
黄金·战略合作赞助	138	享有晚宴VIP独立餐桌与现场展示位	限3家
白银·战略合作赞助	98	享有晚宴标准席位与官方荣誉证书	限6家
指定品类·专项赞助	38	享有晚宴品类独家冠名	独家

Sponsorship Item	Amount (10K RMB)	Specifications / Benefits	Availability
Exhibition Co-organizer Title	60	Exhibition Co-organizer	Exclusive
Exhibition Support Partner	40	Exhibition Supporter	Limited to 3
Diamond - Exclusive Title Sponsor	168	Includes "[Brand Name] Night"	Exclusive
Gold - Strategic Partner	138	VIP dinner table + on-site display booth	Limited to 3
Silver - Strategic Partner	98	Standard dinner seat + official certificate	Limited to 6
Designated Category Sponsor	38	Exclusive category naming rights at dinner	Exclusive

02 外墙广告 Exterior Wall Ads

赞助项目	金额(万元)	规格/权益说明	限量
东登录厅广场广告	80	25.3m×6m入口上方玻璃贴纸	独家
东登录厅广场两侧桁架广告	10	5m×3m两侧桁架	限6家
东登录厅广场左右两侧广告	30	18.1m×15m墙贴	限2家
东登录厅内左右两侧广告	20	18.3m×6m墙贴	限2家
东登录厅正面二层广告	60	13.66m×3.5m墙贴	独家
东/中登录厅展厅通道入口广告	30	20.2m×6m玻璃贴	限2家
中登录厅左右两侧墙面广告	20	55Lm×3.5Hm	限2家
商业通道一层吊旗广告	15	5m×1.5m吊旗	限4家
商业通道一层方形包柱广告	5	1.6×3m方形包柱	限10家

Sponsorship Item	Amount (10K RMB)	Specifications / Benefits	Availability
East Hall Plaza Billboard	80	25.3mx6m entrance glass sticker	Exclusive
East Hall Plaza Truss Ads (both sides)	10	5mx3m truss on both sides	Limited to 6
East Hall Plaza Left & Right Wall Ads	30	18.1mx15m wall sticker	Limited to 2
East Hall Interior Left & Right Wall Ads	20	18.3mx6m wall sticker	Limited to 2
East Hall 2nd Floor Front Wall Ad	60	13.66mx3.5m wall sticker	Exclusive
East/Central Hall Corridor Entrance Ad	30	20.2mx6m glass sticker	Limited to 2
Central Hall Left & Right Wall Ads	20	55Lmx3.5Hm	Limited to 2
Commercial Corridor 1F Hanging Flag Ads	15	5mx1.5m hanging flag	Limited to 4
Commercial Corridor 1F Square Pillar Ads	5	1.6mx3m square pillar	Limited to 10

赞助方案

Sponsorship Proposal

03

馆内外广告

Indoor/Outdoor Hall Ads

赞助项目	金额(万元)	规格/权益说明	限量
8号展厅入口吊旗广告	12	4m×1.5m 6个吊旗	独家
8号展厅入口两侧桁架广告	6	5m×3m桁架	限2家
8号展厅入口门口广告	10	3L×3Hm/5L×3H	独家
8号展厅内部出入口横幅广告	20	17.6m×2.1m墙贴	独家
8号展厅内部出入口包柱广告	12	3m×6m 6个柱子	独家
8号展厅入口右边拐墙贴广告	15	12.2m×10.7m墙贴	独家
8号展厅内部吊旗广告	5	5m×3m 9个吊旗	限9家
7号展厅内部吊旗广告	5	5m×3m 9个吊旗	限9家
6号展厅内部吊旗广告	5	5m×3m 9个吊旗	限9家
6号、7号馆馆间墙贴广告	20	40m×3.1m墙贴广告	独家
5号展厅入口吊旗广告	12	4 m×1.5m 6个吊旗	独家
5号展厅入口两侧桁架广告	6	5m×3m桁架	限2家
5号展厅入口门口广告	10	4.1L×3H/2.5L×3mH 门口+26L×1.5mH 门头	独家
5号展厅内部出入口横幅广告	20	17.6m×2.1m墙贴	独家
5号展厅内部出入口包柱广告	12	3m×6m 6个柱子	独家
5号展厅内部吊旗广告	5	5m×3m 9个吊旗	限9家
5号展厅入口右边拐墙贴广告	15	12.2m×10.7m墙贴	独家
外广场道旗	12	6杆, 树立品牌第一印象	限2家

Sponsorship Item	Amount (10K RMB)	Specifications / Benefits	Availability
Hall 8 Entrance Hanging Flag Ads	12	4mx1.5m (6 flags)	Exclusive
Hall 8 Entrance Truss Ads (both sides)	6	5mx3m truss	Limited to 2
Hall 8 Entrance Door Ad	10	3Lx3Hm/5Lx3Hm	Exclusive
Hall 8 Interior Entrance Banner Ad	20	17.6mx2.1m wall sticker	Exclusive
Hall 8 Interior Entrance Pillar Ads	12	3mx6m (6 pillars)	Exclusive
Hall 8 Entrance Right Corner Wall Ad	15	12.2mx10.7m wall sticker	Exclusive
Hall 8 Interior Hanging Flag Ads	5	5mx3m (9 flags)	Limited to 9
Hall 7 Interior Hanging Flag Ads	5	5mx3m (9 flags)	Limited to 9
Hall 6 Interior Hanging Flag Ads	5	5mx3m (9 flags)	Limited to 9
Hall 6-7 Connecting Wall Ad	20	40mx3.1m wall sticker	Exclusive
Hall 5 Entrance Hanging Flag Ads	12	4mx1.5m (6 flags)	Exclusive
Hall 5 Entrance Truss Ads (both sides)	6	5mx3m truss	Limited to 2
Hall 5 Entrance Door Ad	10	4.1Lx3H/2.5Lx3H door + 26Lx1.5Hmheader	Exclusive
Hall 5 Interior Entrance Banner Ad	20	17.6mx2.1m wall sticker	Exclusive
Hall 5 Interior Entrance Pillar Ads	12	3mx6m (6 pillars)	Exclusive
Hall 5 Interior Hanging Flag Ads	5	5mx3m (9 flags)	Limited to 9
Hall 5 Entrance Right Corner Wall Ad	15	12.2mx10.7m wall sticker	Exclusive
Outdoor Plaza Flag Poles	12	6 poles, strong brand impression	Limited to 2

赞助方案

Sponsorship Proposal

04 登录大厅广告 Lobby Ads

赞助项目	金额(万元)	规格/权益说明	限量
东登录大厅入口LED屏	40	24.96m×1.28m, 人流最密集处	独家
中登录大厅入口LED屏	30	24.96m×1.6m, 第一视觉冲击	独家
展厅主通道喷绘广告	15	4m×7m, 主通道核心位置	限8家
展厅外门口两侧喷绘广告	10	3m×5m, 入口处两边位置	限8家
展厅之间通道喷绘广告	10	3m×6m, 通道两边位置	限24家

Sponsorship Item	Amount (10K RMB)	Specifications / Benefits	Availability
East Lobby Entrance LED Screen	40	24.96mx1.28m, highest foot traffic	Exclusive
Central Lobby Entrance LED Screen	30	24.96mx1.6m, first visual impact	Exclusive
Main Hallway Banner Ad	15	4mx7m, core location	Limited to 8
Hall Entrance Side Banner Ads	10	3mx5m, both sides of entrance	Limited to 8
Hall-to-Hall Corridor Banner Ads	10	3mx6m, both sides of corridor	Limited to 24

05 会议广告 Conference Ads

赞助项目	金额(万元)	规格/权益说明	限量
论坛大屏两侧广告	40	3.5m×2m, 入口处两边位置	限2家
论坛外侧单面广告	15	2m×2m, 入口处两边位置	限10家
论坛椅背套广告位	10	论坛3天参会嘉宾宣传推广	独家
平行论坛	15	分论坛冠名	独家
专场发布会(1.5小时)	6	提供场地、设备及宣传组织	多家
海外买家对接会	0.35	与海外买家精准对接	多家

Sponsorship Item	Amount (10K RMB)	Specifications / Benefits	Availability
Forum Main Stage Side Ads	40	3.5mx2m, entrance sides	Limited to 2
Forum External Single-sided Ad	15	2mx2m, entrance sides	Limited to 10
Forum Chair Back Cover Ad	10	3-day promotion to attendees	Exclusive
Parallel Forum	15	Sub-forum naming rights	Exclusive
Exclusive Press Conference (1.5h)	6	Venue, equipment, promotion	Multiple
Overseas Buyer Matchmaking	0.35	Direct engagement with overseas buyers	Multiple

06 视频广告 Video Ads

赞助项目	金额(万元)	规格/权益说明	限量
深度专访	1.2	3分钟剪辑成片+官媒宣发	多家
展商推荐	6	45秒剪辑成片+官媒宣发	多家

Sponsorship Item	Amount (10K RMB)	Specifications / Benefits	Availability
In-depth Interview	1.2	3-min edited video + official media release	Multiple
Exhibitor Feature	6	45-sec edited video + official media release	Multiple

赞助方案

Sponsorship Proposal

07

印刷广告 Print Ads

赞助项目	金额(万元)	规格/权益说明	限量
参观指南封面广告	15	最高级别印刷品曝光	独家
参观指南封底广告	10	次高级别印刷品曝光	独家
参观指南内页广告	5	精准投放至所有观众	限8家
展商/VIP证赞助	15	单面, 品牌伴随全程	独家

Sponsorship Item	Amount (10K RMB)	Specifications / Benefits	Availability
Visitor Guide Cover Ad	15	Top-tier print exposure	Exclusive
Visitor Guide Back Cover Ad	10	Second-tier print exposure	Exclusive
Visitor Guide Inside Page Ad	5	Targeted reach to all attendees	Limited to 8
Exhibitor/VIP Badge Sponsor	15	Single side, brand visibility throughout	Exclusive

08

品类广告 Category Ads

赞助项目	金额(万元)	规格/权益说明	限量
服装赞助	15	工作人员服装	独家
礼品袋赞助	30	约2万个移动的广告	独家
礼品赞助	20	约2万个展会赠品	独家
伴手礼赞助	30	约1000个嘉宾赠送	独家
咖啡/饮品赞助	10	VIP与海外买家见面会休息区	独家
饮用水赞助	10	瓶身贴标, 品牌触达高频	限2家
奖杯/奖牌/证书赞助	10	优秀展商与合作伙伴授牌	独家
官方指定用车	6	嘉宾接送	独家
合作银行	10	提供相关金融服务	独家
合作航空	20	提供日韩等国航空服务	独家
官方推文合作	5	官方公众号头条发布	多家
官方推文合作	3	官方公众号普通发布	多家

Sponsorship Item	Amount (10K RMB)	Specifications / Benefits	Availability
Apparel Sponsor	15	Staff uniforms	Exclusive
Gift Bag Sponsor	30	~20,000 mobile ads	Exclusive
Giveaway Sponsor	20	~20,000 expo giveaways	Exclusive
Souvenir Sponsor	30	~1,000 gifts for VIPs	Exclusive
Coffee/Beverage Sponsor	10	VIP & overseas buyer lounge	Exclusive
Drinking Water Sponsor	10	Bottle labels, high-frequency brand exposure	Limited to 2
Trophy/Medal/Certificate Sponsor	10	Awards for outstanding exhibitors & partners	Exclusive
Official Designated Vehicle	6	VIP shuttle service	Exclusive
Partner Bank	10	Financial services	Exclusive
Partner Airline	20	Air travel services for Japan, South Korea, etc.	Exclusive
Official WeChat Post Partnership	5	Headline post on official public account	Multiple
Official WeChat Post Partnership	3	Standard post on official public account	Multiple

观众组织

Target Audiences

本次展会将全力邀请全球半导体、集成电路、电子电力、电子制造、显示制造以及汽车、航空航天、医疗卫生、信息通信、消费电子等领域专业人士齐聚杭州，共探前沿科技，共商合作大计，携手解码产业新生态，合力共筑开放、协同、韧性的全球半导体与集成电路产业“芯”未来。

It will attract domestic and foreign professionals from semiconductors, IC, electronic power, electronics manufacturing, display manufacturing, as well as automotive, aerospace, healthcare, information and communications, and consumer electronics industry to participate in the exhibition. The event provides an efficient platform for participants to explore cutting-edge technologies, discuss collaborative strategies, jointly decode the new industrial ecosystem, and work together to build an open, collaborative, and resilient core future for the global semiconductor and IC industry.

芯聚钱塘 智联全球

中国集成电路行业年度标杆采购交流盛会，亚洲极具影响力的芯产业创新、投资、贸易平台
China's annual procurement event for the integrated circuit industry, and one of Asia's most influential platforms for the semiconductor ecosystem to promote innovation, investment, and trade.



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Your timely reservation will allow us to preassign exhibit space. Requests for exhibit space will be accepted on a “first come, first served” basis.

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